

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE9202ED	**Issued**	11. May 2021
MA#	MA001640472		
Package	PG-DSO-36-72	**Weight***	539.97 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	4.399	0.81	0.81	8146	8146
chip_2	inorganic material	silicon	7440-21-3	4.399	0.81	0.81	8146	8146
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.65	44.70	446275	446856
wire	non noble metal	copper	7440-50-8	2.842	0.53	0.53	5263	5263
encapsulation	organic material	carbon black	1333-86-4	0.822	0.15		1522	
	plastics	epoxy resin	-	32.043	5.93		59343	
	inorganic material	silicondioxide	60676-86-0	241.007	44.63	50.71	446337	507202
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12326	12326
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6665	6665
glue	plastics	epoxy resin	-	0.510	0.09		944	
	noble metal	silver	7440-22-4	2.404	0.45	0.54	4452	5396
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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